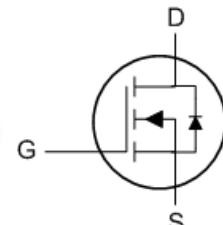
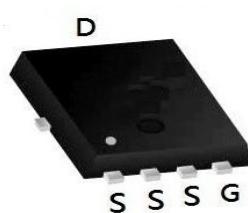


### Product Summary

BVDSS	RDS(ON)	ID
100V	4.5mΩ	100A



### Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low R<sub>DS(ON)</sub>

**PDFN5060-8L**

### Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

### Absolute Maximum Ratings ( $T_c = 25^\circ\text{C}$ , unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V <sub>DS</sub>	100	V
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>c</sub> =25°C	I <sub>D</sub>	100	A
	T <sub>c</sub> =100°C		60	
Pulsed Drain Current <sup>4</sup>		I <sub>DM</sub>	380	A
Single Pulse Avalanche Energy <sup>3</sup>		E <sub>AS</sub>	205	mJ
Total Power Dissipation	T <sub>c</sub> =25°C	P <sub>D</sub>	113.6	W
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	R <sub>θJA</sub>	58	°C/W
Thermal Resistance from Junction-to-Case	R <sub>θJC</sub>	1.1	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)**

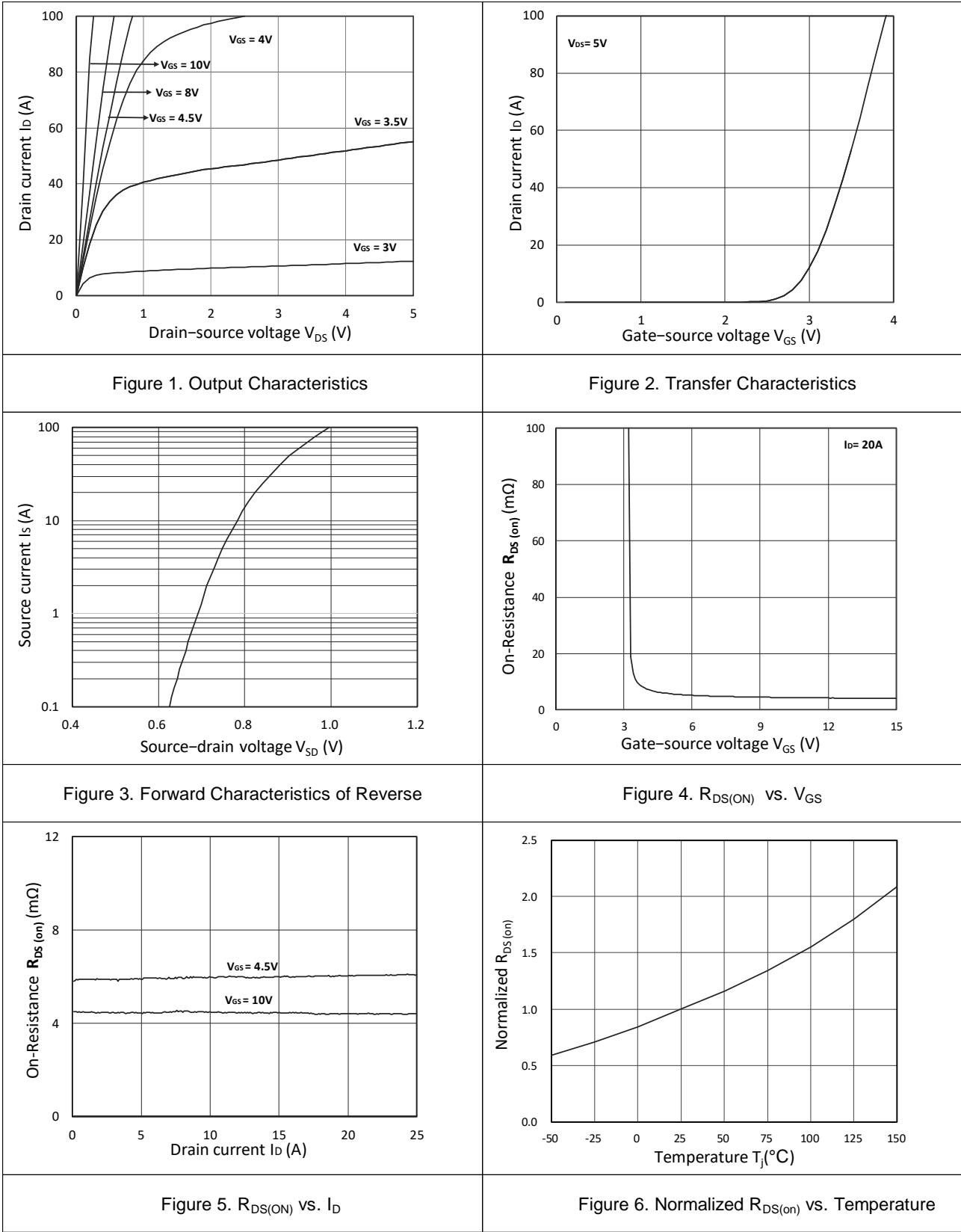
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100	-	-	V
Gate-body Leakage current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current  $T_J=25^\circ\text{C}$ $T_J=100^\circ\text{C}$	$I_{\text{DSS}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	$\mu\text{A}$
			-	-	100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.8	2.5	V
Drain-Source on-Resistance <sup>2</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$	-	4.5	6	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$	-	6.6	9	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	4400	-	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		-	645	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	20	-	
<b>Switching Characteristics</b>						
Gate Resistance	$R_g$	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$	-	1.7	-	$\Omega$
Total Gate Charge	$Q_g$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, I_D = 20\text{A}$	-	75	-	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		-	17	-	
Gate-Drain Charge	$Q_{\text{gd}}$		-	13	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$	-	15.4	-	$\text{ns}$
Rise Time	$t_r$		-	13	-	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		-	34	-	
Fall Time	$t_f$		-	6.2	-	
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>	$I_s$	$V_G = V_D = 0\text{V}$ , Force Current	-	-	95	A
Body Diode Reverse Recovery Time	$t_{\text{rr}}$	$I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	-	55	-	$\text{ns}$
Body Diode Reverse Recovery Charge	$Q_{\text{rr}}$		-	101	-	$\text{nC}$

Notes:

1. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .
2. The EAS data shows Max. rating . The test condition is  $V_{DD}=25\text{V}, V_{GS}=10\text{V}, L=0.4\text{mH}, I_{AS}=40\text{A}$
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$ .
5. This value is guaranteed by design hence it is not included in the production test..

Ver.1.0

## Typical Characteristics



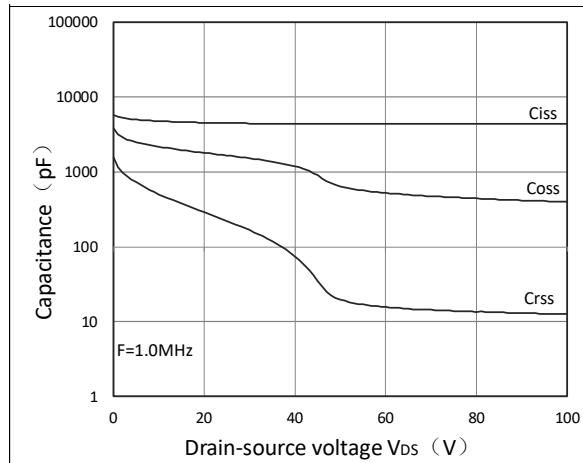


Figure 7. Capacitance Characteristics

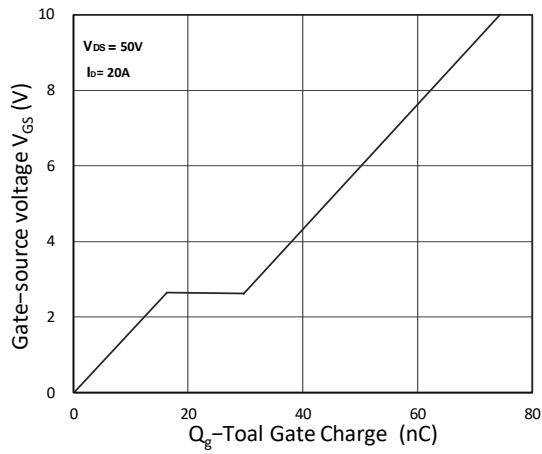


Figure 8. Gate Charge Characteristics

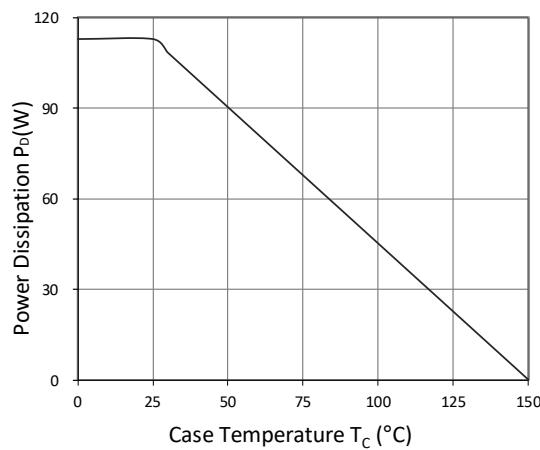


Figure 9. Power Dissipation

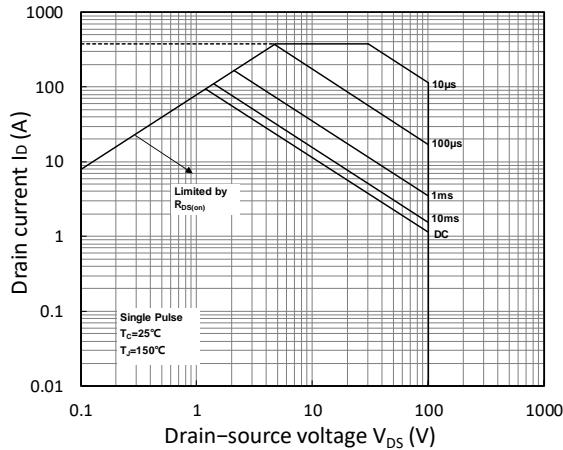


Figure 10. Safe Operating Area

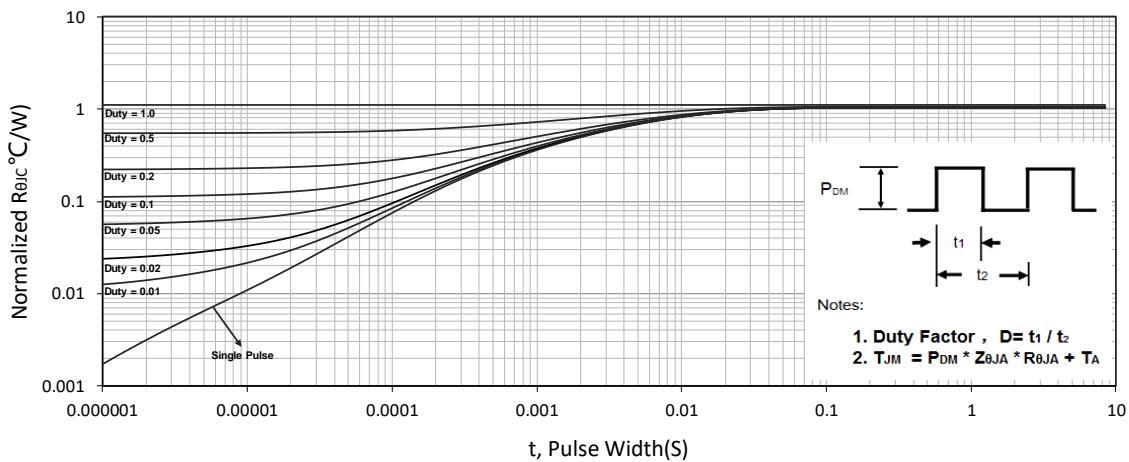
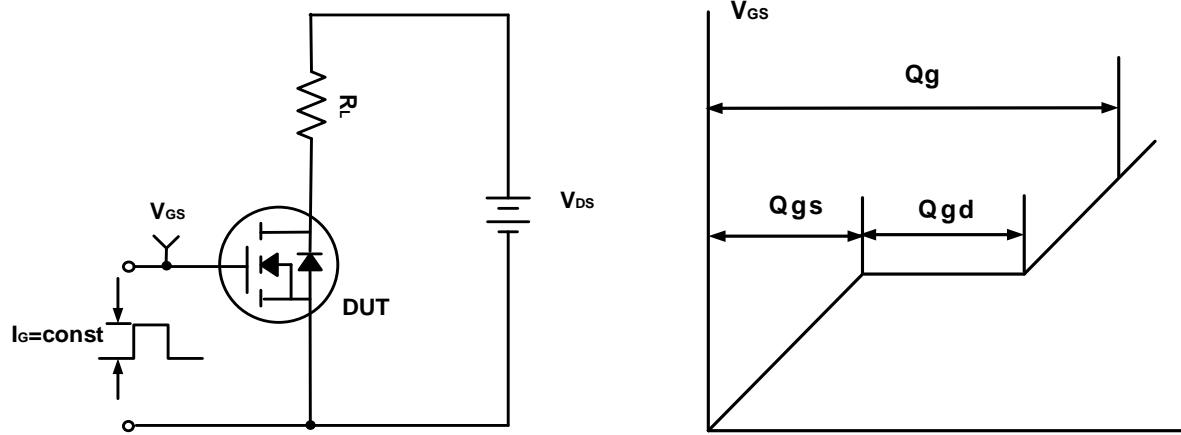
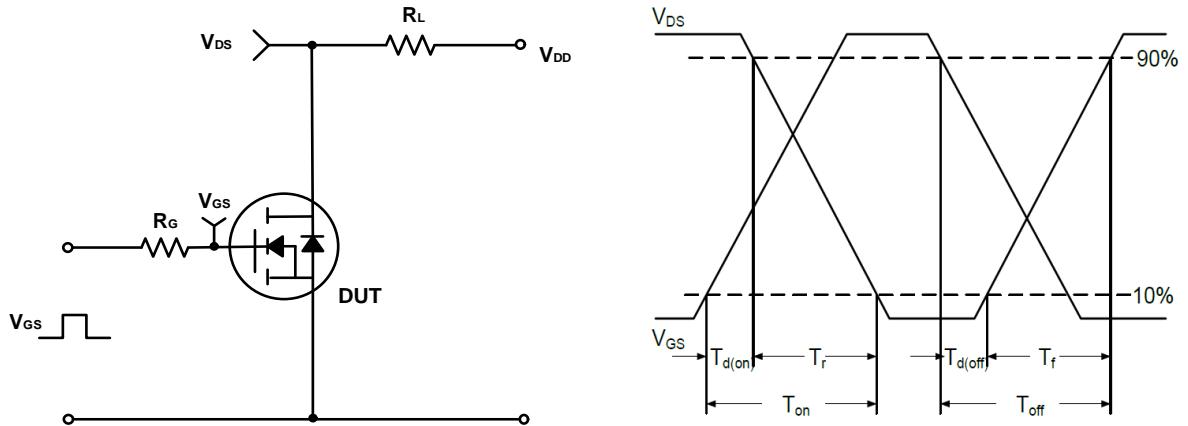
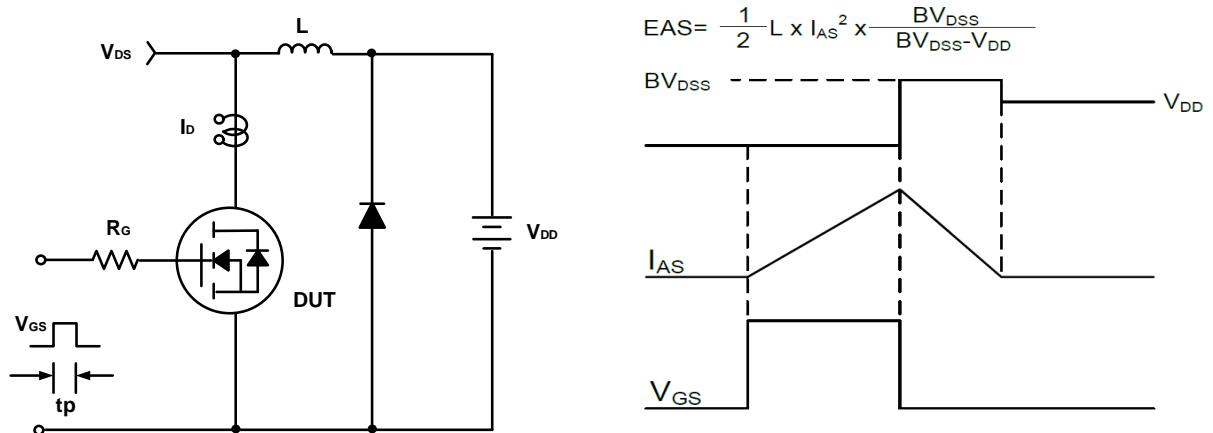
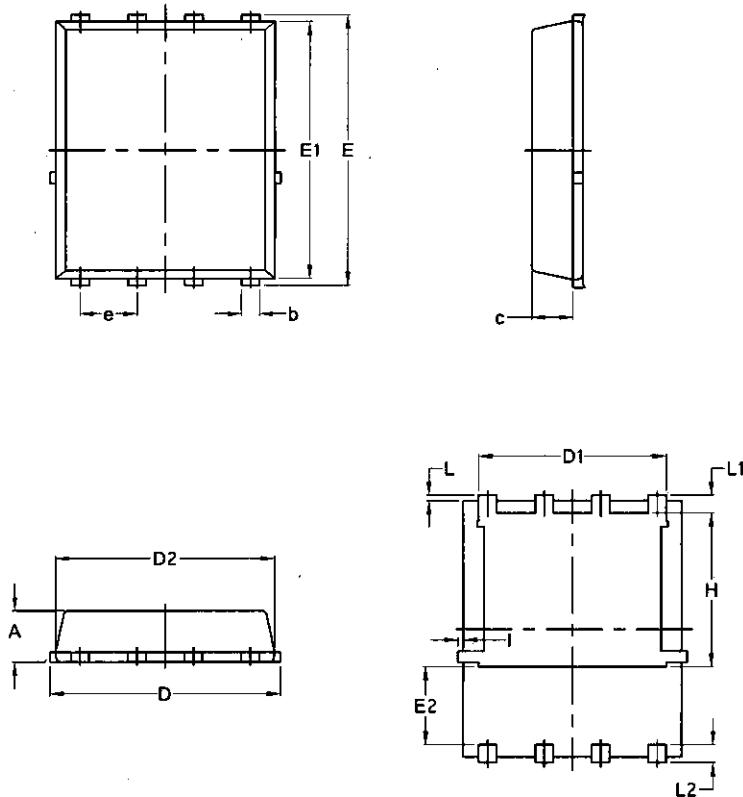


Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit**

**Figure A. Gate Charge Test Circuit & Waveforms**

**Figure B. Switching Test Circuit & Waveforms**

**Figure C. Unclamped Inductive Switching Circuit & Waveforms**

## Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070